

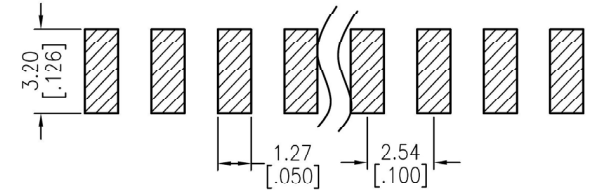
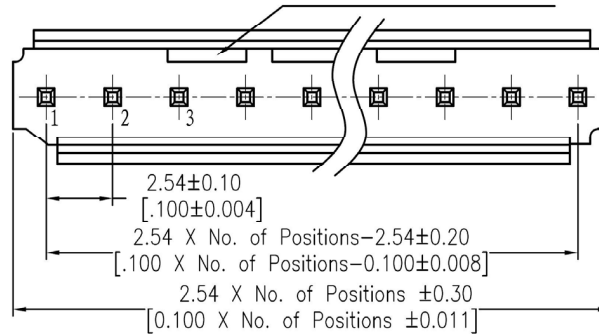
# HSF

The dig material notch changed with position ,not effect the use.

Recommended P.C.B Layout(Top Side)  
(PCB BOARD TOLERANCE±0.05)

NOTES:  
 Rated Current:3A  
 Rated Voltage:250V AC/DC  
 Contact Resistance:20mΩ max  
 Withstand Voltage:1000V AC/Minute  
 Insulation Resistance:1000MΩ min  
 Operation Temperature:-25℃ to+85℃

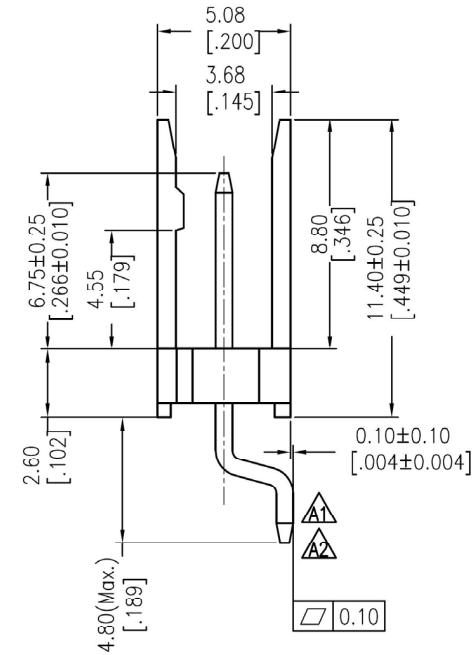
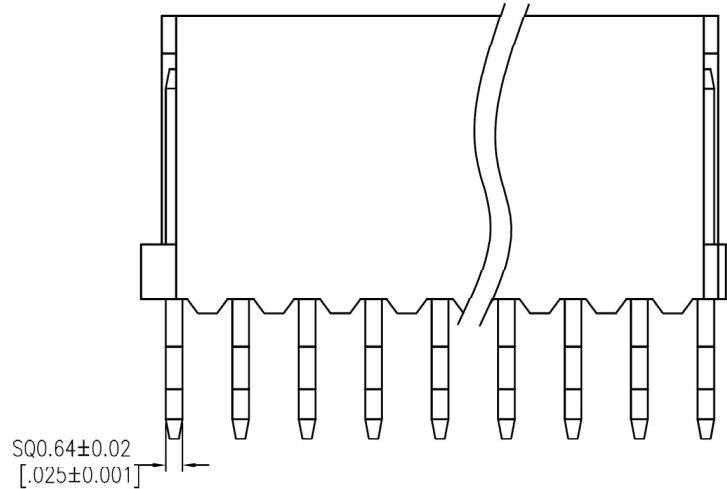
Contact Material:Brass  
 Contact Plating:Au Or Sn over Ni  
 Insulator Material:PA46+15%G.F (UL94V-0)



## Ordering Information

2533 - OS - XX

No. of pins  
 02P-20P  
 Gold Flash  
 Packing REEL



				OPERATION		DRAW	DATE	SCALE	FIT	PART NO. <b>2533 - OS</b>	<b>HO CHIEN</b>
A2	2015/01/05			x.x	±0.40	JYHuang	2015/01/05	UNIT	mm		
A1	2013/10/24			x.xx	±0.25	CHECK	DATE	SIZE	A4	2.54 WAFER SINGLE ROW 90° SMT	
A0	2012/09/19		NEW	x.xxx	±0.15	APPROVE	DATE	SHEET	1/1	"T" TYPE	www.hochien.com
REV	DATE	MODIFICATION	DESCRIPTION	CHANGE	Angle	± 3'		PROJ.	Customer NO.		
					DIM	TOL					